

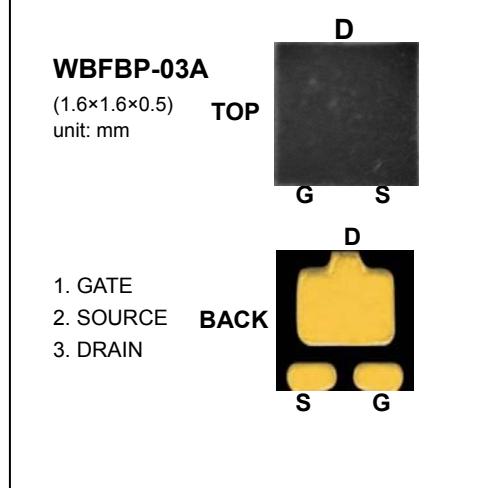
## WBFBP-03A Plastic-Encapsulate MOSFETs

### M7002TTD03

MOSFET( N-Channel )

#### DESCRIPTION

High cell density, DMOS technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance. They can be used in most applications requiring up to 400mA DC and can deliver pulsed currents up to 2A. These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.



#### FEATURES

High density cell design for low  $R_{DS(ON)}$

Voltage controlled small signal switch

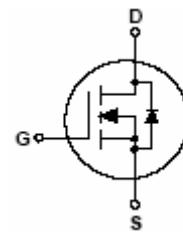
Rugged and reliable

High saturation current capability

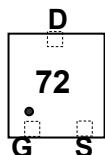
#### APPLICATION

N-Channel Enhancement Mode Field Effect Transistor

For portable equipment:(i.e. Mobile phone,MP3, MD,CD-ROM, DVD-ROM, Note book PC, etc.)



#### MARKING: 72



#### MAXIMUM RATINGS( $T_a=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GSS}$	Gate-Source Voltage - Continuous	$\pm 20$	V
$I_D$	Maximum Drain Current - Pulsed	115	mA
$P_D$	Power Dissipation	150	mW
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	833	$^\circ\text{C}/\text{W}$
$T_J$	Junction Temperature	150	$^\circ\text{C}$
$T_{stg}$	Storage Temperature	-55-150	$^\circ\text{C}$



## ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =10μA	60			V
		V <sub>GS</sub> =0V, I <sub>D</sub> =3mA	60			
Gate-Threshold Voltage*	V <sub>(GS)th</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1			
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±25V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V			1	μA
		V <sub>DS</sub> =60V, V <sub>GS</sub> =0V, T <sub>j</sub> =125°C			500	
On-state Drain Current*	I <sub>D(ON)</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =7V	500			mA
Drain-Source On-Resistance*	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =500mA	1		7.2	Ω
		V <sub>GS</sub> =5V, I <sub>D</sub> =50mA	1		7.2	
Drain-Source On- Voltage *	V <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =500mA			3.75	V
		V <sub>GS</sub> =5V, I <sub>D</sub> =50mA			0.375	
Forward Tranconductance*	g <sub>fs</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =200mA	80			ms
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =115mA, V <sub>GS</sub> =0V			1.2	V
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1MHz			50	pF
Output Capacitance	C <sub>oss</sub>				25	
Reverse Transfer Capacitance	C <sub>rss</sub>				5	
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =10V, I <sub>D</sub> =250mA			1	nC
Gate-Source Charge	Q <sub>gs</sub>				25	
Gate-Drain Charge	Q <sub>d</sub>				5	

\*Pulse test , pulse width≤300μs, duty cycle≤2% .

## SWITCHING TIME

Turn-on Time	t <sub>d(on)</sub>	V <sub>DD</sub> =25V, R <sub>G</sub> =25Ω I <sub>D</sub> =500mA, V <sub>GEN</sub> =10V R <sub>L</sub> =50Ω			20	ns
Turn-off Time	t <sub>d(off)</sub>				40	